



## P-Channel 12-V (D-S) MOSFET

MOSFET PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
	0.035 at V <sub>GS</sub> = - 4.5 V	- 5.1			
- 12	0.045 at V <sub>GS</sub> = - 2.5 V	- 4.5	9 nC		
	0.059 at V <sub>GS</sub> = - 1.8 V	- 3.9			

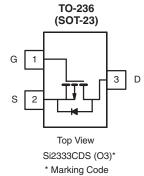
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



#### **APPLICATIONS**

- Load Switch
- PA Switch



Ordering Information: Si2333CDS-T1-E3 (Lead (Pb)-free) Si2333CDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 12	V		
Gate-Source Voltage		V <sub>GS</sub>			± 8
	T <sub>C</sub> = 25 °C		- 7.1		
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	$T_C = 70  ^{\circ}C$	l <sub>s</sub>	- 5.7		
Continuous Brain Carrent (1) = 100 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 5.1 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		- 4.0 <sup>b, c</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	- 20		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	l <sub>a</sub>	- 1.0		
Continuous Source-Diam blode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 0.63 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		2.5		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	P <sub>D</sub>	1.6	w	
	T <sub>A</sub> = 25 °C	' Б	1.25 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		0.8 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		$T_{,l}, T_{sta}$	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	≤ 5 s	$R_{thJA}$	75	100	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	40	50		

- a. Based on  $T_C = 25$  °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under Steady State conditions is 166 °C/W.

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MOSFET SPECIFICATIONS  Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	Oyinboi	rest conditions	IVIIII.	Typ.	WIGA.	Onic
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>DS</sub> = 0 V, I <sub>D</sub> = - 250 μA	- 12			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 13		
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		2.6		mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 0.4		- 1	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 8 V			± 100	nA
Zero Gate Voltage Drain Current	400	V <sub>DS</sub> = - 12 V, V <sub>GS</sub> = 0 V			- 1	μΑ
	I <sub>DSS</sub>	V <sub>DS</sub> = - 12 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 20			Α
	. ,	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.1 A		0.0285	0.035	Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 4.5 A		0.036	0.045	
	, ,	V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 2.0 A		0.046	0.059	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 5.3 A		18.5		S
Dynamic <sup>b</sup>					L	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = - 6 V, V <sub>GS</sub> = 0 V, f = 1 MHz		1225		pF
Output Capacitance	C <sub>oss</sub>			315		
Reverse Transfer Capacitance	C <sub>rss</sub>			260		
Total Cata Charge	V <sub>D0</sub> = - 6	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5.1 \text{ A}$		15	25	
Total Gate Charge	Q <sub>g</sub>			9	15	20
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -6 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -5.1 \text{ A}$		1.9		nC
Gate-Drain Charge	$Q_{gd}$			3.8		
Gate Resistance	$R_g$	f = 1 MHz		4.0		Ω
Turn-On Delay Time	t <sub>d(on)</sub>			13	20	
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 6 V, $R_L$ = 6 $\Omega$		35	60	- ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D$ = - 1 A, $V_{GEN}$ = - 4.5 V, $R_G$ = 1 $\Omega$		45	70	
Fall Time	t <sub>f</sub>	7		12	20	
<b>Drain-Source Body Diode Characteristi</b>	cs					
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 1.0	А
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 20	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 1.0 A		- 0.7	- 1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			32	50	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = - 1.0 A, dI/dt = 100 A/μs, T <sub>J</sub> = 25 °C		20	40	nC
Reverse Recovery Fall Time	t <sub>a</sub>	i <sub>F</sub> = 1.0 Δ, αί/αι = 100 Δ/μ5, 1J = 25 °C		16		
Reverse Recovery Rise Time	t <sub>b</sub>	7		16		ns

#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

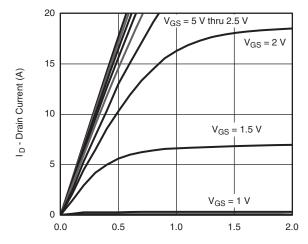
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





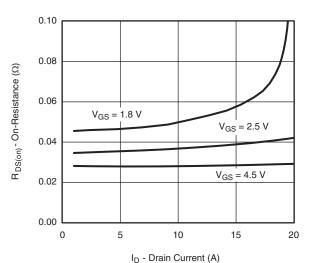


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

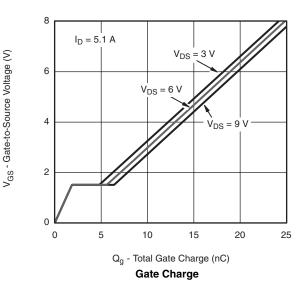


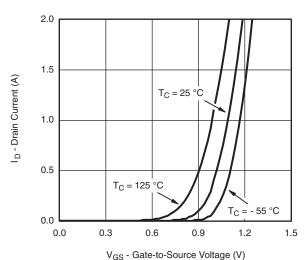
V<sub>DS</sub> - Drain-to-Source Voltage (V)

#### **Output Characteristics**



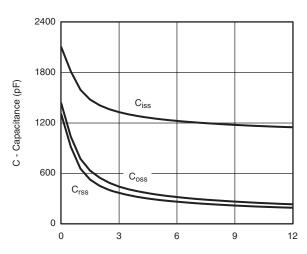
On-Resistance vs. Drain Current and Gate Voltage





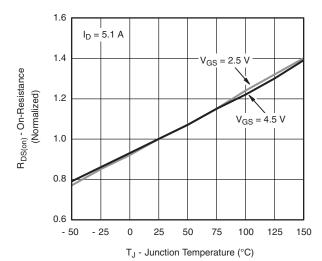
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#### **Transfer Characteristics**



 $V_{\mbox{\footnotesize DS}}$  - Drain-to-Source Voltage (V)

#### Capacitance

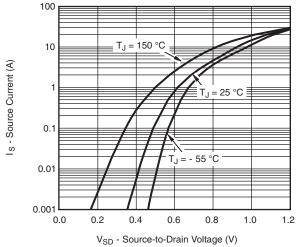


On-Resistance vs. Junction Temperature

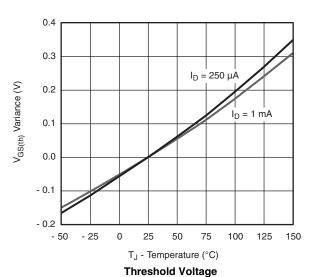
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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



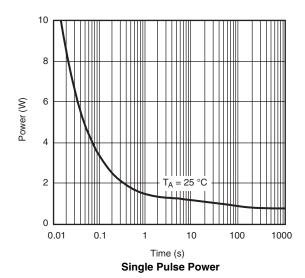
Source-Drain Diode Forward Voltage

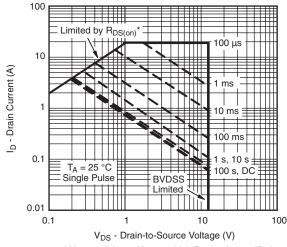


0.14 0.12 0.10 0.08 0.08 0.06 0.06 0.04 0.02 0.00 0 1 2 3 4 5

V<sub>GS</sub> - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



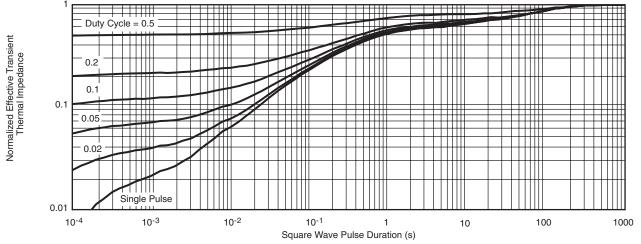


\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

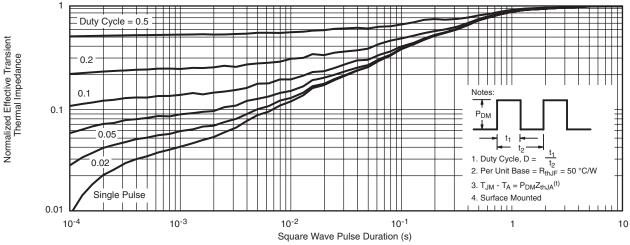
Safe Operating Area



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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